



## Material Content Data Sheet



Sales Product Name	BSS670S2L H6327			Issued		23. January 2020		
MA#	MA001422274							
Package	PG-SOT23-3-5			Weight*		9.36 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.004	0.04		403	
	noble metal	gold	7440-57-5	0.015	0.16		1564	
	inorganic material	silicon	7440-21-3	0.223	2.39	2.59	23863	25830
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		64	
	non noble metal	titanium	7440-32-6	0.003	0.03		322	
	non noble metal	chromium	7440-47-3	0.009	0.10		966	
	non noble metal	copper	7440-50-8	3.000	32.07	32.21	320657	322009
wire	non noble metal	copper	7440-50-8	0.007	0.08	0.08	768	768
encapsulation	organic material	carbon black	1333-86-4	0.057	0.60		6050	
	plastics	epoxy resin	-	1.217	13.01		130076	
	inorganic material	silicondioxide	60676-86-0	4.387	46.87	60.48	468879	605005
leadfinish	non noble metal	tin	7440-31-5	0.150	1.60	1.60	15992	15992
plating	noble metal	silver	7440-22-4	0.284	3.04	3.04	30396	30396
*deviation	< 10%	Sum in total:				100.00		1000000

### Important Remarks:

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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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